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### IN THE UNITED STATES PATENT & TRADEMARK OFFICE

pplication Number

10/724,133

Confirmation No. 1214

Applicant

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Joon Hyeon LEE

December 1, 2003

Filed

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Tech Cntr/AU

1765

Examiner

Duy Vu Nguyen Deo

Entitled

METHOD OF FORMING METAL LINE LAYER IN

SEMICONDUCTOR DEVICE

Attorney Reference

123034-05004921

Customer Number

43569

## **MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

# **AMENDMENT/RESPONSE TRANSMITTAL**

Transmitted herewith is an amendment/response for this application.

#### **EXTENSION OF TIME**

A petition for extension of time under 37 C.F.R. 1.136 is not believed necessary.

#### **CLAIM FEES**

The claim fees have been calculated as follows:

Total	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR		PRESENT EXTRA		RATE		ADDITIONAL FEE		
			20	=	0	x \$	50.00	=	\$	0.00
Independent	11	_	3	=	0_	x \$	200.00	=	\$	0.00
	FIRST PRES	ENTATIO	ON OF MULT	TIPLE DE	P. CLA	IM+ \$	360.00	=	\$	0.00
	TOTAL ADDITIONAL CLAIM FEE DUE								\$	0.00

#### **FEE PAYMENT**

Authorization is given herein to charge the any deficiencies in the fees not specifically authorized herein, or to further credit any overpayments, to Deposit Account No. <u>503-121</u> in order to maintain the pendency of this application.

Intellectual Property Department Mayer Brown Rowe & Maw LLP 1909 K Street, N.W. Washington, D.C. 20006-1101 Yoon S. Ham Registration No. 45,307 (202) 263-3280

Date: October 18, 2005

OTPE 48 0005 NOTE

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P.O. Box 1450

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### RESPONSE UNDER 37 C.F.R. § 1.111

Sir:

In response to the Office Action dated July 20, 2005 for the above-identified application, amendments and/or remarks submitted herewith include:

- In the Drawings;
- · A complete claim listing; and
- Remarks and arguments.